Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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DB4J310K

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Low forward voltage V_F
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4A

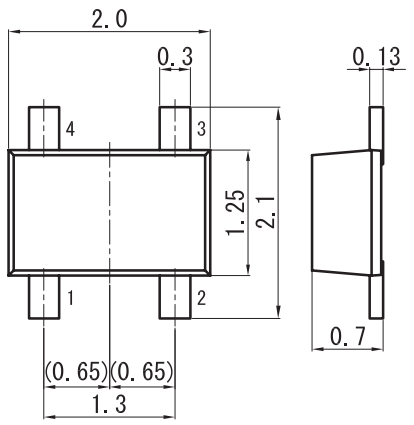
■ Basic Part Number

Dual DB2J310 (Parallel)

■ Packaging

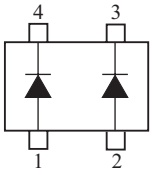
DB4J310K0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Unit: mm



1: Anode-1
2: Anode-2
3: Cathode-2
4: Cathode-1

Panasonic	SMini4-F3-B
JEITA	SC-113BB
Code	—



■ Absolute Maximum Ratings $T_a = 25°C$

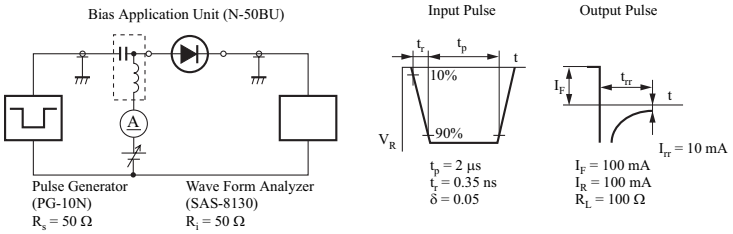
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Repetitive peak reverse voltage		V_{RRM}	30	V
Forward current (Average)	Single	$I_{F(AV)}$	200	mA
	Double *1		150	mA
Peak forward current	Single	I_{FM}	300	mA
	Double *1		225	mA
Non-repetitive peak forward surge current *2		I_{FSM}	1	A
Junction temperature		T_j	125	°C
Operating ambient temperature		T_{opr}	–40 to +85	°C
Storage temperature		T_{stg}	–55 to +125	°C

Note) ∗1: Value of each diode in double diodes used.
∗2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

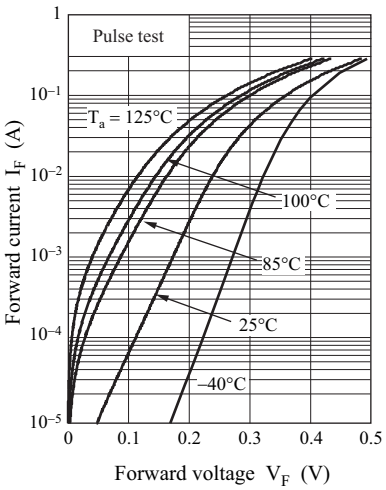
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 5 mA			0.27	V
	V_{F2}	I_F = 100 mA			0.40	
	V_{F3}	I_F = 200 mA			0.47	
Reverse current	I_{R1}	V_R = 10 V			20	μA
	I_{R2}	V_R = 30 V			200	
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		4.5		pF
Reverse recovery time *1	t_{rr}	$I_F = I_R$ = 100 mA, I_{rr} = 10 mA, R_L = 100 Ω		1.6		ns

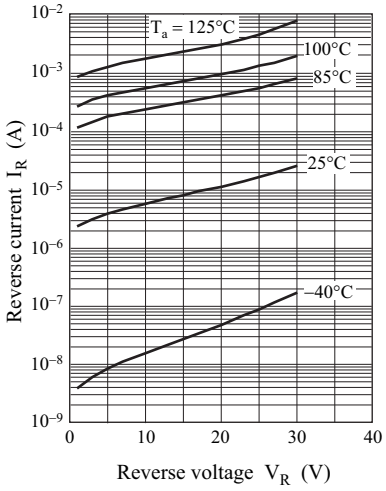
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
∗1: t_{rr} measurement circuit



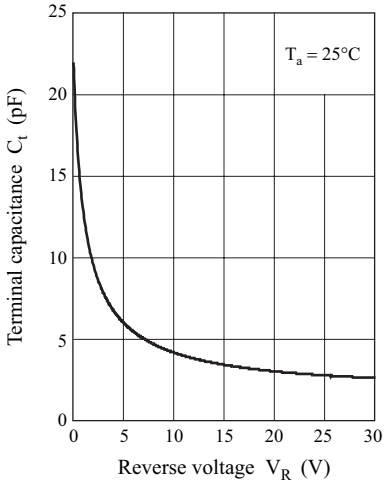
I_F — V_F



I_R — V_R

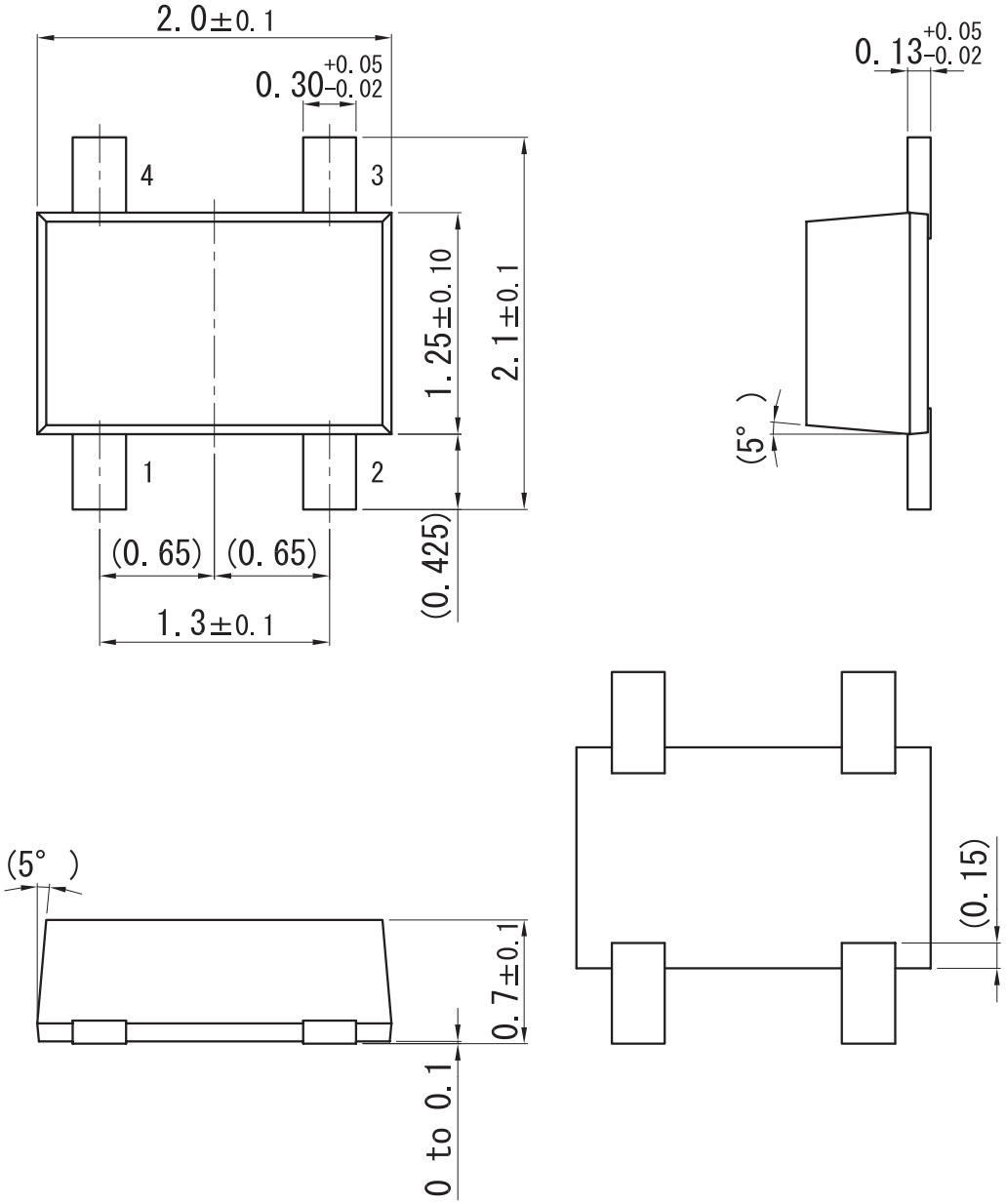


C_t — V_R

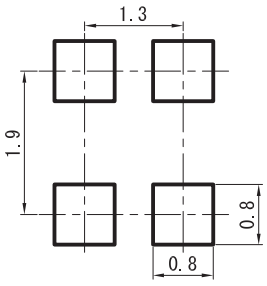


SMini4-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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